

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
31 March 2005 (31.03.2005)

PCT

(10) International Publication Number  
**WO 2005/029573 A1**

(51) International Patent Classification<sup>7</sup>: **H01L 21/4763**,  
21/285, 23/36, 23/367, 23/373, 31/024, 31/052, 31/18,  
H01S 5/024

(21) International Application Number:  
PCT/SG2003/000223

(22) International Filing Date:  
19 September 2003 (19.09.2003)

(25) Filing Language: English

(26) Publication Language: English

(71) Applicant (for all designated States except US): **TINGGI TECHNOLOGIES PRIVATE LIMITED** [SG/SG]; 83 Science Park Drive, #03-01/02, The Curie, Science Park 1, Singapore 118258 (SG).

(72) Inventors; and

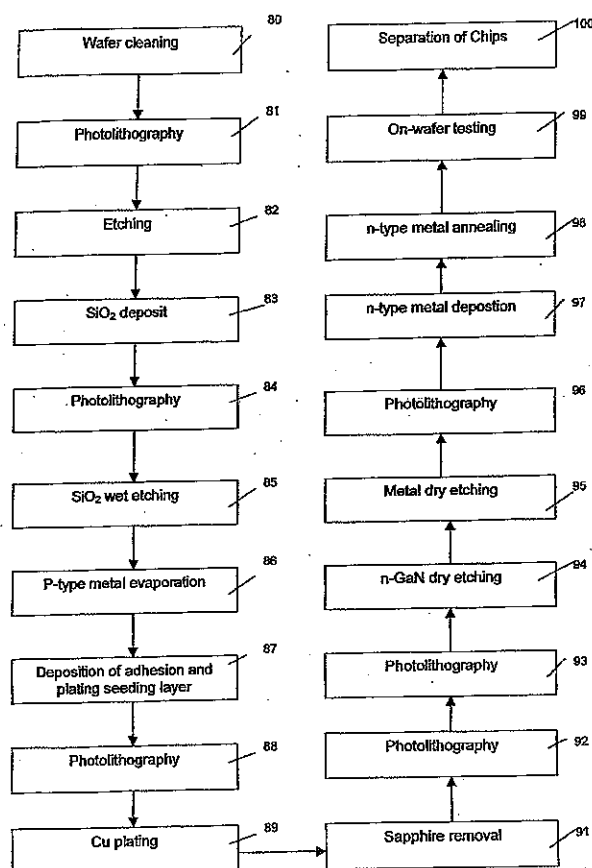
(75) Inventors/Applicants (for US only): **KANG, Xuejun** [CN/SG]; Block 509, West Coast Drive, #11-277, Singapore 120509, 120509 Singapore (SG). **WU, Daike** [CN/SG]; Block 527, Jelepang Road, #07-603, Singapore 670527, 670527 Singapore (SG). **PERRY, Edward Robert** [US/US]; 2440 Sanborn Drive, Sedona, Arizona 86336, USA, Sedona, AZ 86336 (US).

(74) Agent: **ALBAN TAY MAHTANI & DE SILVA**; 39 Robinson Road, #07-01 Robinson Point, Singapore 068911, 068911 Singapore (SG).

(81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT,

[Continued on next page]

(54) Title: FABRICATION OF SEMICONDUCTOR DEVICES



(57) Abstract: A method for fabrication of a semiconductor device on a substrate, the semiconductor having a wafer. The method includes the steps: (a) applying a seed layer of a thermally conductive metal to the wafer; (b) electroplating a relatively thick layer of the conductive metal on the seed layer; and (c) removing the substrate. A corresponding semiconductor device is also disclosed.

WO 2005/029573 A1



RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR,  
TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

- (84) **Designated States (regional):** ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Declaration under Rule 4.17:**

— *of inventorship (Rule 4.17(iv)) for US only*

**Published:**

— *with international search report*

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